



BUR920000082US2 (13647A)

Confirmation No.
3166

P11LARGE/REV09



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Wadgi W. Abadeer, et al. **Examiner:** Vinh P. Nguyen

Serial No: 10/801,387

Art Unit: 2829

Filed: March 16, 2004

Docket: BUR920000082US2(13647A)

For: A WAFER LEVEL SYSTEM FOR
PRODUCING BURN-IN/SCREEN,
AND RELIABILITY EVALUATIONS
TO BE PERFORMED ON ALL CHIPS
SIMULTANEOUSLY WITHOUT ANY
WAFER CONTACTING

Dated: January 13, 2005

Confirmation No.: 3166

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT UNDER 37 C.F.R. 1.111

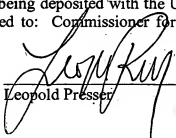
Sir:

In response to the Office Action of October 19, 2004, applicants respectively request that the following amendments be entered into this application:

CERTIFICATE OF MAILING UNDER 37 C.F.R. §1.8(a)

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Dated: January 13, 2005


Leopold Presser